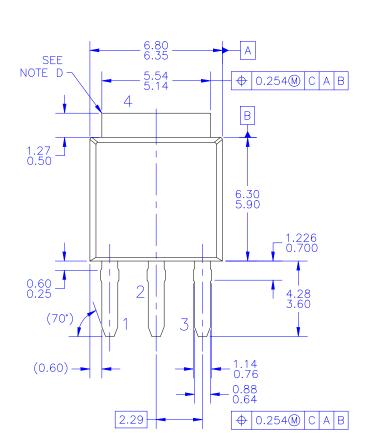
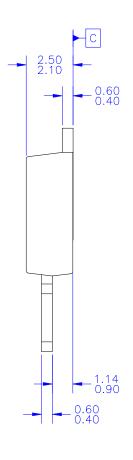
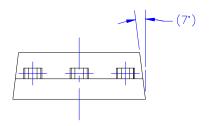


## DPAK3 (STRAIGHT LEADS) CASE 369AP ISSUE O

**DATE 30 SEP 2016** 







NOTES: UNLESS OTHERWISE SPECIFIED

- A) ALL DIMENSIONS ARE IN MILLIMETERS.
- B) PACKAGE BODY REFERENCE: JEDEC, TO-251, ISSUE D, VARIATION AA, DATED JUNE 2002.
- DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
- D) HEAT SINK TOP EDGE COULD BE IN CHAMFERED CORNERS OR EDGE PROTRUSION.

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DESCRIPTION:	DPAK3 (STRAIGHT LEADS)		PAGE 1 OF 1

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